

Product Change Notice

Issue Date: November 6, 2018

Change Type:

Add Assembly Production Site – ASE Shanghai

Parts Affected:BCM58101B0KFBG
BCM58101LB0KFBG
BCM58101LB0KFBGT**Description and Extent of Change:**

Add ASE Shanghai as an additional assembly supplier for the above devices. We expect the change to be a drop in replacement. ASE Shanghai is in mass production for the above package technology.

Reasons for Change:

Capacity at the current site Amkor China could not meet the increasing demand. The additional site is necessary for supply.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification will be performed on representative products to ensure normal parametric distribution, consistent electrical performance, and reliability.

Effective Date of Change:

Product shipments using this change will begin after February 17, 2019. Timing of shipment of the changed part will vary by part number depending on qualification completion, customer demand, and inventory levels.

Qualification Data:

Package Qualification Reference	PQ004255
Fab Technology	40nm
Package Type	FBGA
Package Size	10mm x 10mm
Lead Count	196

Stress Test	Condition	Read points	Sample Size	Requirements	Results (#fail/ss)
		Cycles / Hrs.			
Precondition	MSL3 JESD22-A113E	Post MSL3 Precon	160 units	0 failures	0 / 160
Temp Cycle	-55°C / 125°C JEDEC Std 22-A104-C Cond. B	1000 cycles	77 units	0 failures	0 / 77
Unbiased HAST	130°C, 85% RH, JEDEC Std 22-A118	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150°C JEDEC Std 22-A103-C	1000 hrs	77 units	0 failures	0 / 77